Product End-of-Life Disassembly Instructions

Product Category: Personal Computers
Marketing Name / Model **[List multiple models if applicable.]**
HP Omni 200 PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm Mother board,Ram,Brightness board,Converter board,Power board	5
Batteries	All types including standard alkaline and lithium coin or button style batteries Coin cell battery	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps LCD panel	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0

Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screwdriver	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove Hinge-door.
2. Release screws for Stand-ASSY, then remove Stand-ASSY
3. Remove HDD-door and Memory-door.
4. Release screw for ODD-module, then use screw driver to push ODD-module out of system.
5. Release screws for Postponement-door, then remove Postponement-door ASSY.
6. Release screw for Rear I/O cover, then remove Rear I/O cover ASSY.
7. Release screws for rear cover, then remove rear cover ASSY.
8. Release screws for inverter, and then remove inverter.(Figure 4)
9. Release screws for Brightness BKT, then remove Brightness ASSY.(Figure 3)
10. Release screws for FAN module, then remove it.
11. Release screws fro Thermal module, then remove it.
12. Release screws for M/B shielding, then remove M/B shielding.(Figure 1)
13. Release RTC battery form motherboard.(Figure 1: highlighted in red zone)
14. To remove ram form M/B.(Figure 2)
15. Release screws for Bluetooth module, Antenna, Camera module and Speaker, then remove all of them.
16. Release screw for HDD, then remove HDD ASSY.
17. Release screw for Power board, then remove it.(Figure 5)
18. Release screws form Panel-ASSY to Bezel, then remove Panel-ASSY.
19. Release screws for Panel-ASSY, then remove middle-frame.(Figure 6)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

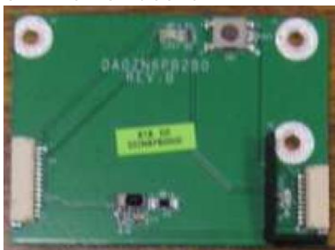
1. Motherboard

2. Ram

3. Brightness board

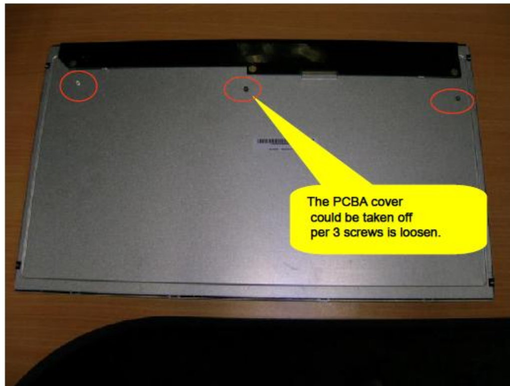
4. Inverter board

5. Power board

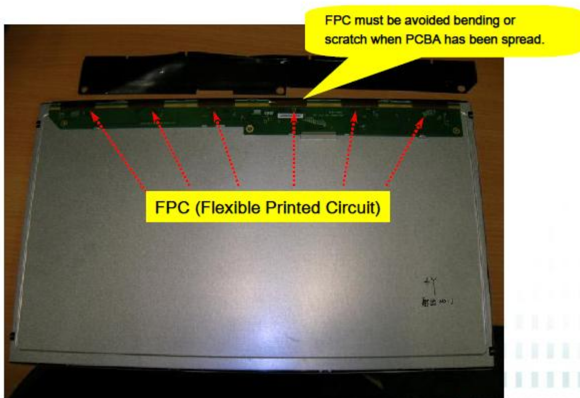


6. LCD panel disassembly process

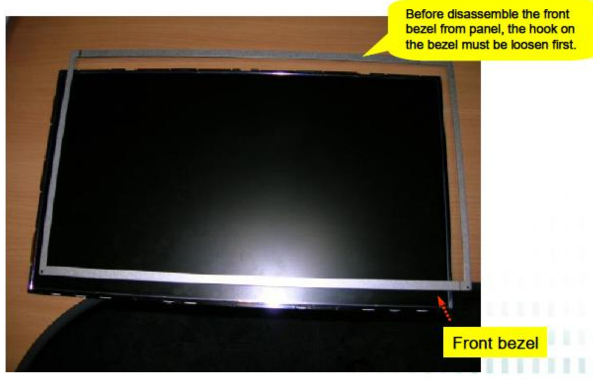
1.Remove screws in the shielding plat of panel



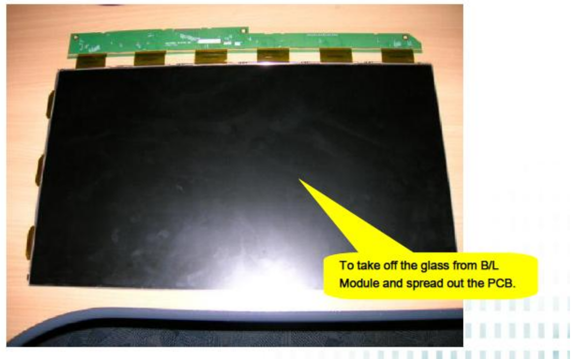
2. Tear off the PCBA mylar



3.Remove the front bezel



4. Take off the TFT glass from B/L module



5. Take off frame from B/L module